

Sub c17

ABSTRACT OF THE DISCLOSURE

An electronic package that may include a first bond pad and a second bond pad located on a bond shelf. The bond shelf may have an edge. The package may have a first conductive bus that may be connected to the first bond pad by a first conductive strip that extends along the edge of the bond shelf. The package may also have a second conductive bus that may be connected to the second bond pad by a second conductive strip that extends along the edge of the bond shelf.

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